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To the A	Assistant Commissioner of Patents. Please record the	e attachec	101039146	
TAK Addition 3. Nat	me of conveying party(ies): (ESHI MAKITA and SATOSHI MAEDA mal name(s) of conveying party(ies) attached? Yes X No ture of Conveyance: signment Merger curity Agreement Change of Name	Name: Interd Stree	ne and address of receiving par SONY CORPORATION nal Address: Tokyo Internationa 100-31, Japan t Address: 7-35, Kitashinagaw Tokyo 141 Country	al P.O. Box 5100, Tokyo wa 6-chome, Shinagawa-ku
Oth	ecution Date: March 23, 1999	Addit	Additional Name(s) & address(es) attached? Yes X No	
	Patent Application No.(s): 09/254,750 International Filing Date: July 10, 1998 Additional numbers attached?	B.	Patent No.(s)	
5. Nam doc	me and address of party to whom correspondence concer cument should be mailed:	rning 6. Tot	al number of applications and	patents involved: 1
Str Cit Tel	re: Charles P. Sammut, Esquire dernal Address: Limbach & Limbach L.L.P. deet Address: 2001 Ferry Building dery, State, ZIP: San Francisco, California 94111 dephone: (415) 433-4150 desimile: (415) 433-8716	X	Enclosed Authorized to be charged to	deposit account
Att	Attorney Docket No. TNAB-P8716		duplicate copy of this page if paying b	
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<u>M</u> ay	yumi Maeda, Reg. No. 40,075 Name of Person Signing	Signatur		ay 6, 1999 Date ing cover sheet: 1

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Docket Number:	TNAB-P8716

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in DATA PROCESSING APPARATUS AND DATA PROCESSING METHOD for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address; AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo 141-0001, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries; NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto; And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto; And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense; And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto; And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale. And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 09/254,750, Filing Date: This assignment executed on the dates indicated below. TAKESHI MAKITA Name of first or sole inventor Execution date of U.S. Patent Application Kanagawa, Japan Residence of first or sole inventor 23. Mar. 1999 Jokeshi Makita
Signature of first or sole inventor

PATENT

Date of this assignment

REEL: 009947 FRAME: 0435

SATOSHI MAEDA		
Name of second inventor	Execution date of U.S. Patent Application	
Kanagawa, Japan		
Residence of second inventor		
Signature of second inventor	23 4 MAR '89	
Signature of second inventor	23 th MAR '99 Date of this assignment	
Name of third inventor	Execution date of U.S. Patent Application	
Residence of third inventor		
Signature of third inventor	Date of this assignment	
Name of fourth inventor	Execution date of U.S. Patent Application	
Residence of fourth inventor		
Signature of fourth inventor	Date of this assignment	
Name of fifth inventor	Execution date of U.S. Patent Application	
Residence of fifth inventor		
Signature of fifth inventor	Date of this assignment	

RECORDED: 05/10/1999

PATENT REEL: 009947 FRAME: 0436

Date of this assignment